SO-8

Top View

S<sub>2</sub> [



## SM4803DSKC-TRG-VB Datasheet

# **Dual N-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
30	0.010 at V <sub>GS</sub> = 10 V	13.5	5.9 nC		
30	$0.012 \text{ at V}_{GS} = 4.5 \text{ V}$	11	3.9110		

D<sub>1</sub>
D<sub>1</sub>
D<sub>2</sub>

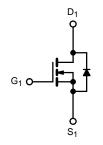
5 D<sub>2</sub>

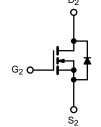
#### **FEATURES**

- · Halogen-free
- Trench Power MOSFET
- Optimized for High-Side Synchronous Rectifier Operation
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

- Notebook CPU Core
  - High-Side Switch





N-Channel MOSFET

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25  ^{\circ}C$ , unless Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30			
Gate-Source Voltage	V <sub>GS</sub>	± 20			
	T <sub>C</sub> = 25 °C	- 50	12		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C	1-	11		
Continuous Dialit Current (1) = 130 C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	10 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		8 <sup>b, c</sup>	^	
Pulsed Drain Current		I <sub>DM</sub>	45	A	
Continuous Source Drain Diada Current	T <sub>C</sub> = 25 °C	1-	3.2		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	1.6 <sup>b, c</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	17		
Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	21	mJ	
	T <sub>C</sub> = 25 °C		4.1		
Maximum Daylor Dissination	T <sub>C</sub> = 70 °C	P <sub>D</sub>	2.5	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		2.1 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		1.2 <sup>b, c</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	39	53	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	25	29	C/VV	

## Notes:

- a. Base on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 °C/W.



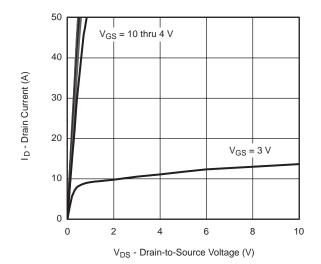
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		,					
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		28		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	ι <sub>D</sub> = 250 μΑ		- 6			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.2		2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valta na Duain Commant		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	μА	
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	T <sub>J</sub> = 55 °C		10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
	_	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		0.010		_	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 9 A		0.012		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		52		S	
Dynamic <sup>b</sup>					l		
Input Capacitance	C <sub>iss</sub>			641		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		175			
Reverse Transfer Capacitance	C <sub>rss</sub>			73			
	Qg	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		15	23	nC	
Total Gate Charge				6.8	10.2		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 10 \text{ A}$		2.5			
Gate-Drain Charge	Q <sub>gd</sub>			2.3			
Gate Resistance	$R_g$	f = 1 MHz	0.36	1.8	3.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			16	24		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.4 \Omega$		12	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 9 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		16	24		
Fall Time	t <sub>f</sub>			10	20	1	
Turn-On Delay Time	t <sub>d(on)</sub>			8	16	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.4 \Omega$		10	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 9 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	24		
Fall Time	t <sub>f</sub>			8	15		
<b>Drain-Source Body Diode Characterist</b>	ics			1	•		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			17	^	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				45	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 9 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			15	30	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			6	12	nC	
Reverse Recovery Fall Time	$t_{a}$ $t_{F} = 9 \text{ A, dl/dt} = 100 \text{ A/µs, T}_{J} = 100  A/$			8			
Reverse Recovery Rise Time	1	t <sub>b</sub>		7		ns	

#### Notes

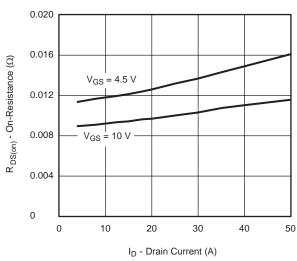
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

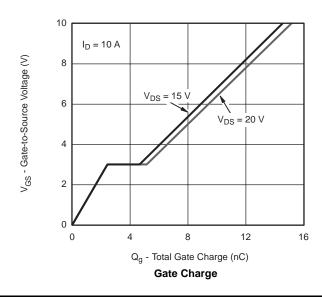




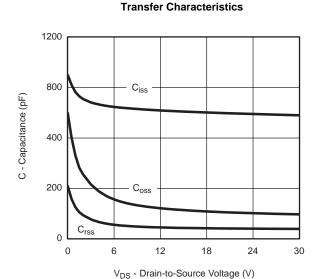
#### **Output Characteristics**



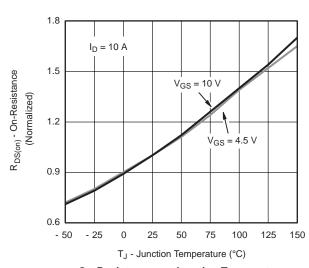
On-Resistance vs. Drain Current and Gate Voltage



 $V_{GS}$  - Gate-to-Source Voltage (V)

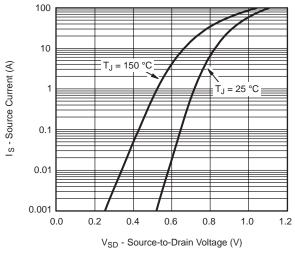


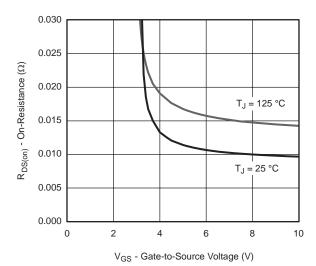
Capacitance



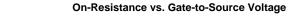
On-Resistance vs. Junction Temperature

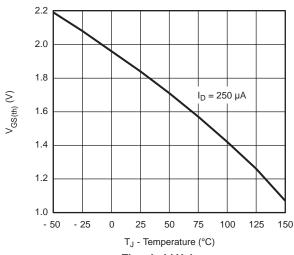


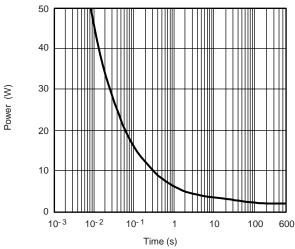




#### Source-Drain Diode Forward Voltage

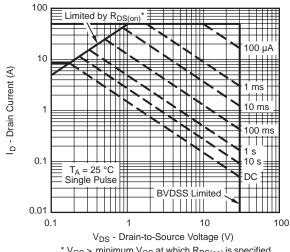






#### **Threshold Voltage**

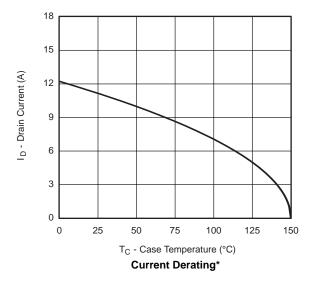
Single Pulse Power, Junction-to-Ambient



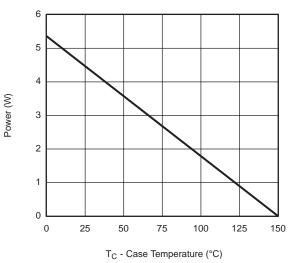
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

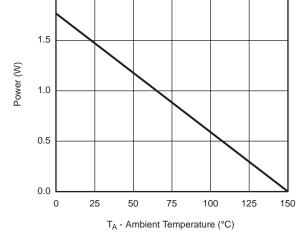
Safe Operating Area, Junction-to-Ambient





2.0



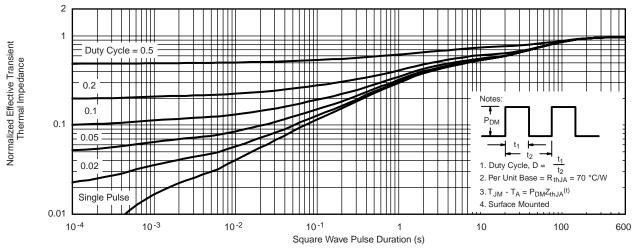


Power Derating, Junction-to-Foot

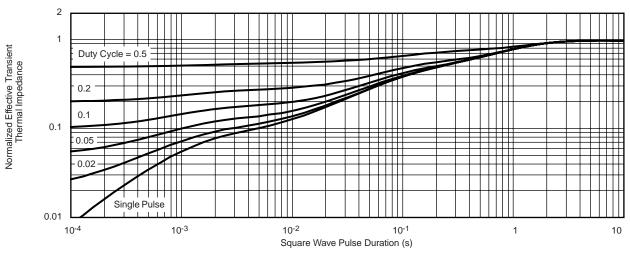
Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

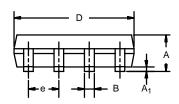


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







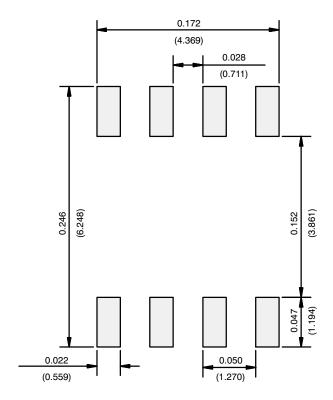
	MILLIM	IETERS	INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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